

ABSTRACT OF THE DISCLOSURE

A semiconductor device including a substrate having a main surface including a first area, a second area surrounding the first area, and a third area surrounding the second area; a first insulating protective film that is provided in the first area and formed in a shape having no angles; a second insulating protective film provided in the third area; a semiconductor chip that is provided on the first insulating protective film and has a bottom surface facing to the first insulating protective film; and a sealing resin covering the semiconductor chip, wherein the bottom surface of the semiconductor chip covers the first area.